

TB67S213FTAG

Usage considerations

Summary

The TB67S213FTAG is a Phase-in controlled two-phase bipolar stepping motor driver using a PWM chopper. Fabricated with the BiCD process, rating is 40 V/2.5A.

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4. PWM control

The TB67S213FTAG can adjust the internal oscillation frequency (f_{OSCM}) and the chopping frequency (f_{chop}) with the constant number of the external parts connecting to OSCM terminal.

- The relation equations of the OSCM oscillation frequency (f_{OSCM}) and the chopping frequency (f_{chop}) are as follows;

-

$$f_{OSCM} = 1 / [0.56 \times \{C \times (R1 + 500)\}]$$

$$f_{chop} = f_{OSCM} / 16$$

* C, R1: external constant number for OSCM (f_{OSCM} is about 1.6MHz (typ.) at C = 270 pF and R1 = 3.6 kΩ. f_{chop} becomes considerable at about 100 kHz (typ.))

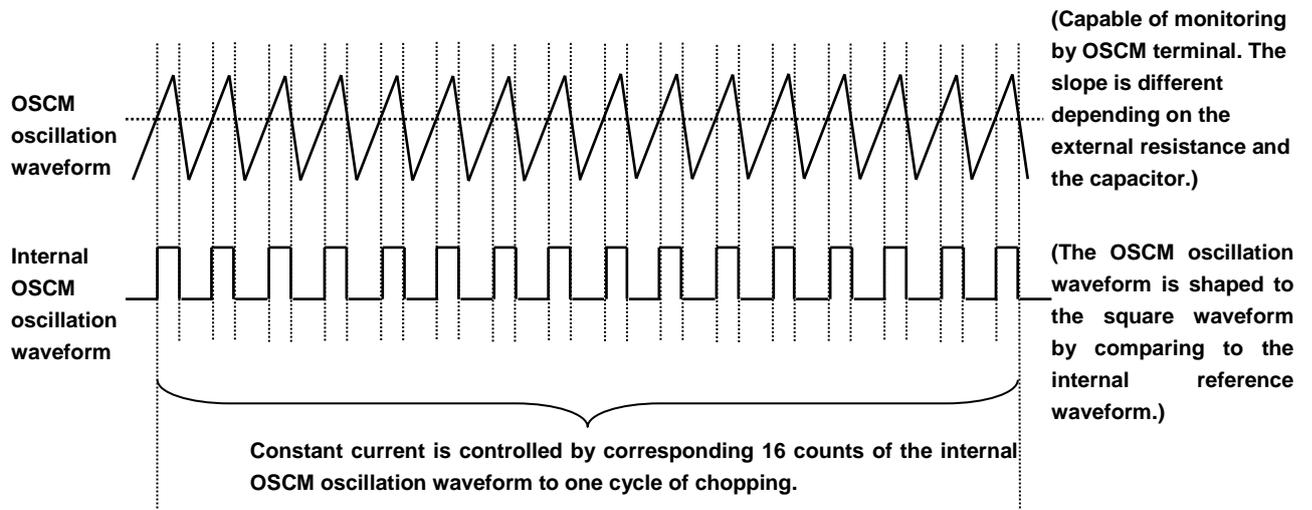


Figure 4.1 OSCM oscillation frequency

When the chopping frequency is increased, the motor can rotate faster because the following capability of the current steps increases. However, switching loss and heat increase may occur because the number of switching of output MOSFET is larger than the case of low frequency of the chopping.

(Example 1) Chopping frequency (f_{chop}) = 100 kHz

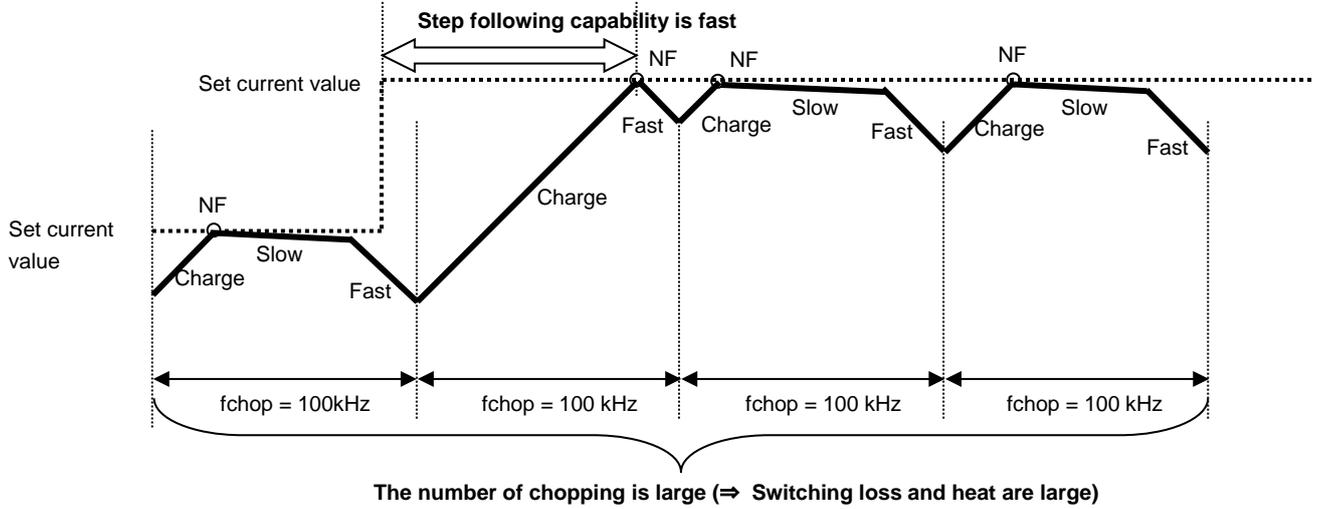


Figure 4.2 Chopping frequency (100 kHz)

(Example 2) Chopping frequency (f_{chop}) = 50 kHz

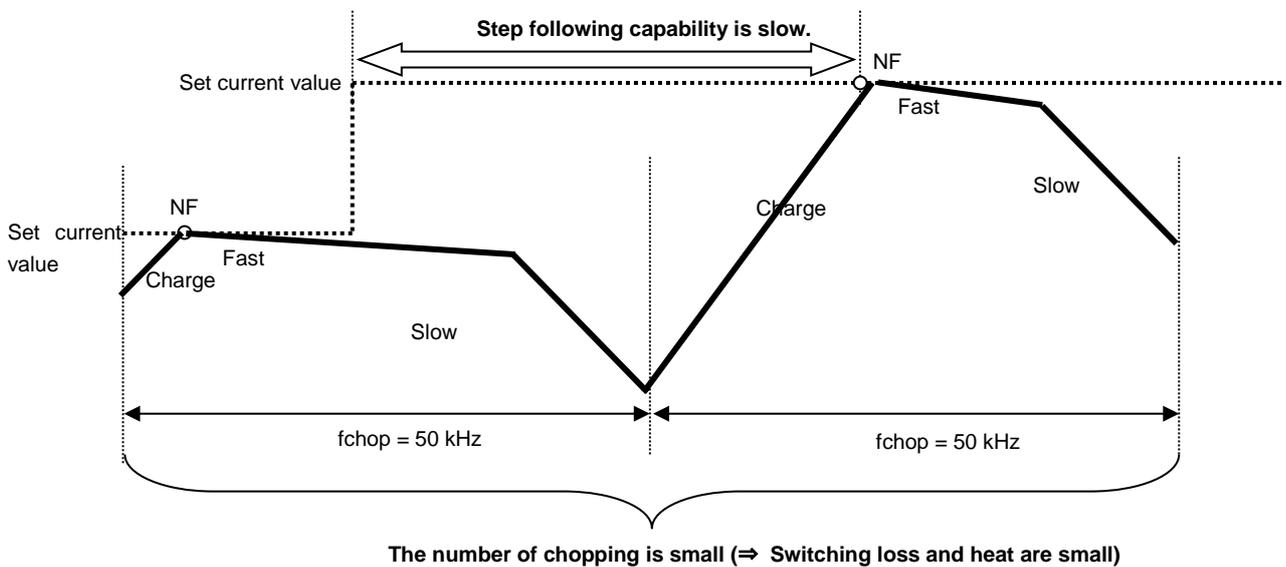


Figure 4.3 Chopping frequency (50 kHz)

Generally, it is recommended to configure the frequency in the range of 50 kHz to 100 kHz on the basis of 70kHz.

5. Mixed Decay control

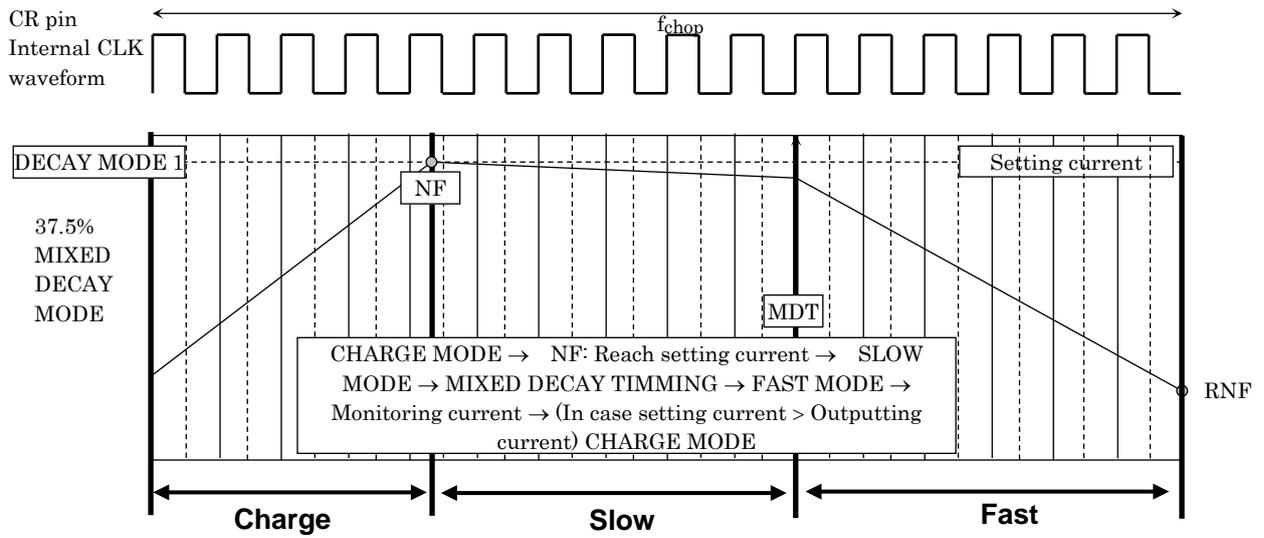


Figure 5.1 Mixed Decay control

6. Switching characteristics

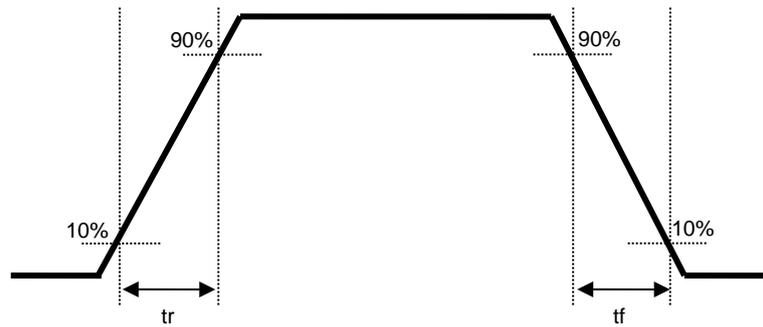


Figure 6.1 Switching characteristics

Table 6.1 Switching characteristics

T_a = 25°C, V_M = 24 V, No load

Item	Typ.	Unit
tr	150	ns
tf	100	ns

7. Function explanation

(1) Input-and-output function list

IOUT: The flow from OUT_A(OUT_B) to OUT_A-(OUT_B-) is plus current. The flow from OUT_A-(OUT_B-) to OUT_A(OUT_B) is minus current.

Table 7.1 Input-and-output function table

Input			Output		
PHASE_A PHASE_B	IN_A1 IN_B1	IN_A2 IN_B2	OUT_A OUT_B	OUT_A- OUT_B-	Iout(A) Iout(B)
H	H	H	H	L	100%
	H	L	H	L	71%
	L	H	H	L	38%
	L	L	Output OFF	Output OFF	0%
L	H	H	L	H	-100%
	H	L	L	H	-71%
	L	H	L	H	-38%
	L	L	Output OFF	Output OFF	0%

(2) STANDBY function

In Standby mode, an internal oscillating circuit and a motor output part are stopped. (The drive of a motor cannot be performed.)

Table 7.2 STANDBY function

STANDBY Input	Function
H	Standby release
L	Standby mode

(3) The control sequence in each drive mode

Table 7.3 Full step

Ach				Bch			
Input			Output	Input			Output
PHASE_A	IN_A1	IN_A2	lout(A)	PHASE_B	IN_B1	IN_B2	lout(B)
H	H	H	+100%	H	H	H	+100%
L	H	H	-100%	H	H	H	+100%
L	H	H	-100%	L	H	H	-100%
H	H	H	+100%	L	H	H	-100%

Table 7.4 Half step

Ach				Bch			
Input			Output	Input			Output
PHASE_A	IN_A1	IN_A2	lout(A)	PHASE_B	IN_B1	IN_B2	lout(B)
H	H	H	+100%	H	H	H	+100%
X	L	L	0%	H	H	H	+100%
L	H	H	-100%	H	H	H	+100%
L	H	H	-100%	-	L	L	0%
L	H	H	-100%	L	H	H	-100%
X	L	L	0%	L	H	H	-100%
H	H	H	+100%	L	H	H	-100%
H	H	H	+100%	-	L	L	0%

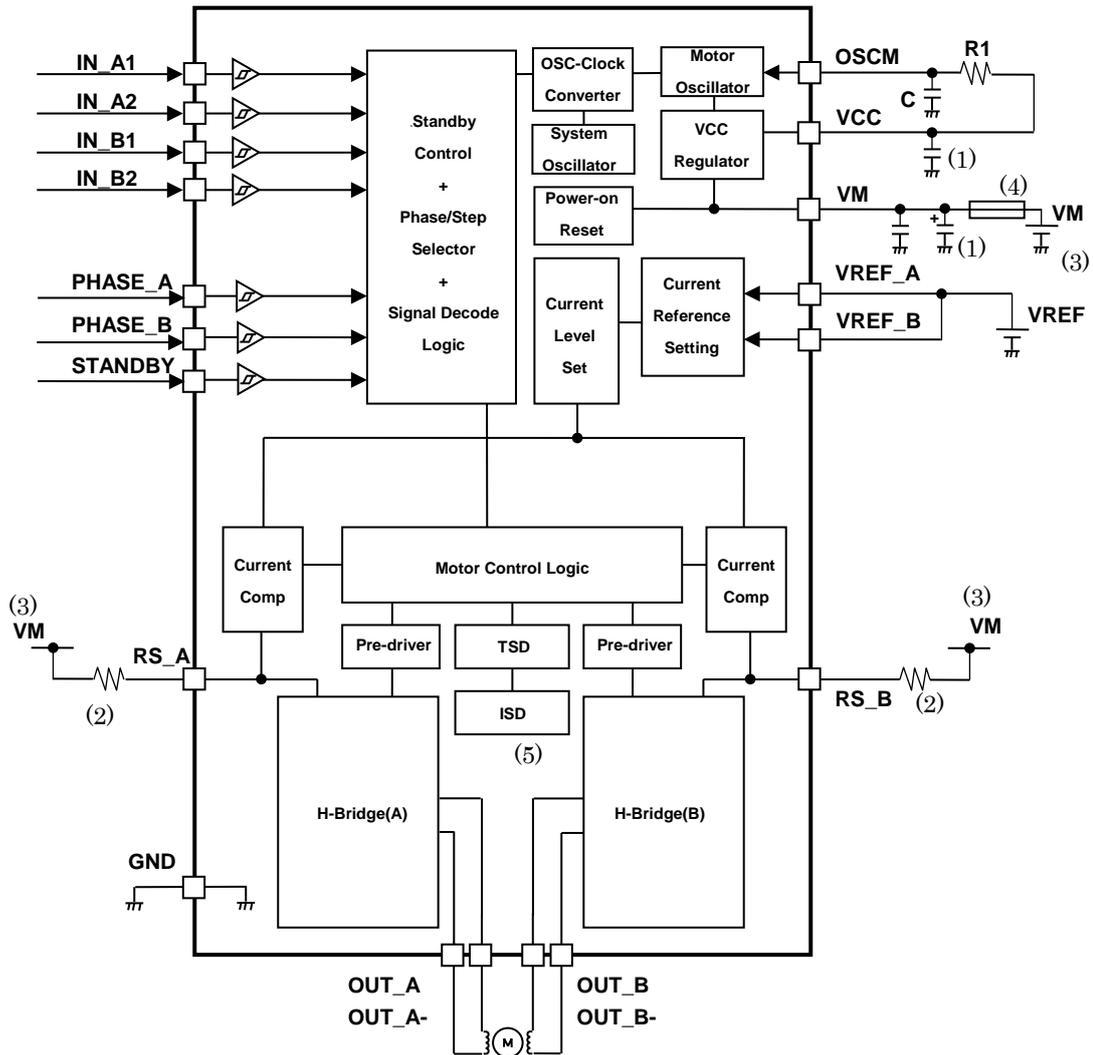
X: Don't care

Table 7.5 Quarter step

Ach				Bch			
Input			Output	Input			Output
PHASE_A	IN_A1	IN_A2	lout(A)	PHASE_B	IN_B1	IN_B2	lout(B)
H	H	L	+71%	H	H	L	+71%
H	L	H	+38%	H	H	H	+100%
X	L	L	0%	H	H	H	+100%
L	L	H	-38%	H	H	H	+100%
L	H	L	-71%	H	H	L	+71%
L	H	H	-100%	H	L	H	+38%
L	H	H	-100%	X	L	L	0%
L	H	H	-100%	L	L	H	-38%
L	H	L	-71%	L	H	L	-71%
L	L	H	-38%	L	H	H	-100%
X	L	L	0%	L	H	H	-100%
H	L	H	+38%	L	H	H	-100%
H	H	L	+71%	L	H	L	-71%
H	H	H	+100%	L	L	H	-38%
H	H	H	+100%	X	L	L	0%
H	H	H	+100%	H	L	H	+38%

X: Don't care

8. Application circuit example



The application circuits shown in this document are provided for reference purposes only. Thorough evaluation is required, especially at the mass-production design stage.

Figure 8.1 Example of application circuit

(1) Capacitor for power supply terminal

To stabilize the power supply voltage of the IC and reduce the noise, connect the appropriate capacitor to each terminal. It is recommended to connect the capacitor as close to the IC as possible. Especially, by connecting the ceramic capacitor near the IC, the change of the power supply at the high frequency range and the noise can be reduced.

Table 8.1 Recommended capacitor values for power supply terminal

Item	Parts	Typ.	Recommended range
Between VM and GND	Electrolytic capacitor	100 μF	47 to 100 μF
	Ceramic capacitor	0.1 μF	0.01 to 1 μF
Between VCC and GND	Ceramic / Electrolytic capacitor	0.1 μF	0.01 to 1 μF
(Between VREF and GND)	Ceramic capacitor	0.1 μF	0.01 to 1 μF

* Between VREF and GND: Connect the capacitor in necessary depending on the usage environment.

* It is possible to use the capacitor, which is not the recommended capacitor, depending on the motor load condition and the design pattern of the board.

(2) Resistance of current detection

This IC configures the threshold of the constant current detection by connecting the resistance of current detection between VM and RS terminals. The detection resistance is recommended to connect near the IC. (The motor can be controlled with the accurate current because the influence of the wire resistance of the board can be reduced.)

Table 8.2 Recommended resistance values for current detection

Item	Parts	Typ.	Recommended range
VM-RS	Chip / Lead resistance	0.22 Ω (0 to 2.5A)	0.22 to 0.51 Ω

The relation equation of the threshold of the constant current detection, Vref voltage, and the resistance of RS detection is as follows;

$$I_{out(max)} = V_{ref(gain)} \times \frac{V_{ref(V)}}{R_{RS}(\Omega)}$$

Vref(gain): Vref decay ratio is 1 / 5.0(typ.).

As for the resistance of current detection, the constant number which is out of recommended range can be adopted. In this case, please pay attentions to the followings when the used resistance is high and low.

- When the detection resistance is low, the difference voltage between VM and RS comparing to the internal reference voltage becomes small. So, the current may be largely different from the configured current value.
- When the detection resistance is high, the power applied to the detection resistance increases in motor operation ($P=I^2 \times R$). So, in case the same current flows as the case of low resistance, the power dissipation should be larger.

(3) Wiring pattern for power supply and GND

Since large current may flow in VM, RS, and GND pattern especially, design the appropriate wiring pattern to avoid the influence of wiring impedance. It is very important for surface mounting package to radiate the heat from the heat sink of the back side of the IC to the GND. So, design the pattern by considering the heat design.

(4) Fuse

Use an appropriate power supply fuse for the power supply line to ensure that a large current does not continuously flow in the case of over-current and/or IC failure.

The IC will fully break down when used under conditions that exceed its absolute maximum ratings, when the wiring is routed improperly or when an abnormal pulse noise occurs from the wiring or load, causing a large current to continuously flow and the breakdown can lead to smoke or ignition. To minimize the effects of the flow of a large current in the case of breakdown, appropriate settings, such as fuse capacity, fusing time and insertion circuit location, are required.

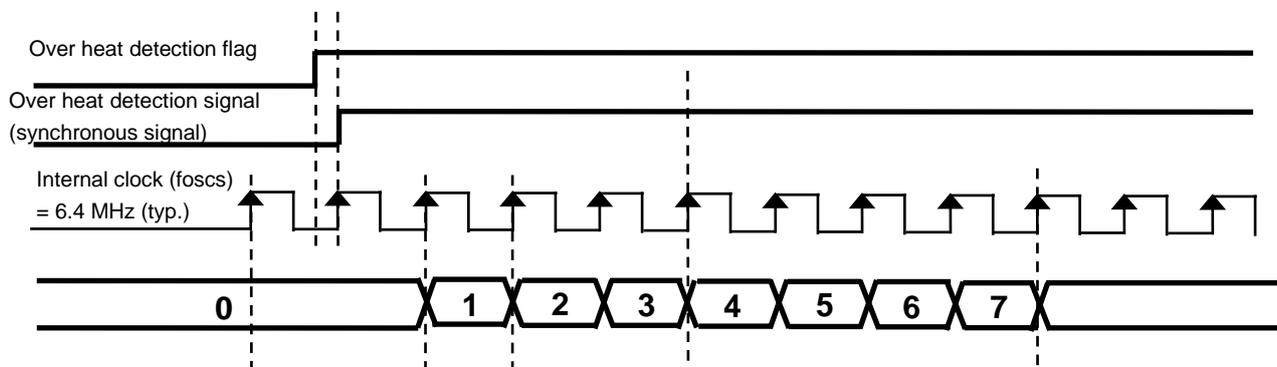
This IC incorporates over current detection circuit (ISD) that turns off the output of the IC when over current is detected in the IC. However, it does not necessarily protect ICs under all circumstances. If the Over current detection circuits operate against the over current, clear the over current status immediately. Depending on the method of use and usage conditions, such as exceeding absolute maximum ratings can cause the over current detection circuit to not operate properly or IC breakdown before operation. In addition, depending on the method of use and usage conditions, if over current continues to flow for a long time after operation, the IC may generate heat resulting in breakdown.

To avoid above IC destruction and malfunctions caused by noise, the over current detection circuit has a dead band time. So, it is concerned that the over current detection circuit may not operate depending on the output load conditions because of the dead band time. Therefore, in order to avoid continuing this abnormal state, use the fuse for the power supply line.

(5) Abnormality detection function

- Thermal shutdown circuit (TSD)**
 When the IC detects an over temperature, the internal circuit turns off the output MOSFETs. It has a dead band time to avoid TSD misdetection, which may be triggered by external noise. Reassert the VM power supply or use the standby mode by STANDBY terminal to release this function. The TSD is triggered when the device is over heated irregularly. Make sure not to use the TSD function aggressively.
- Over current detection (ISD)**
 When the IC detects an over current, the internal circuits turns off the output MOSFETs. It has a dead band time to avoid ISD misdetection, which may be triggered by external noise. Reassert the VM power supply or use the standby mode by STANDBY terminal to release this function.

Dead band time of ISD



Timing charts may be simplified for explanatory purposes.

Figure 8.2 Dead band time of ISD

ISD has a dead band time to avoid false detection caused by spike current in switching. This dead band time is configured by counting up the internal counter by the fixed frequency (6.4 MHz(typ.)) in the IC.

- * $f_{oscs} = 6.4 \text{ MHz (typ.)}$ internal clock
 $1 / f_{oscs} \times 7 \text{ to } 8 \text{ clk}$ (1.09 to 1.25 μs)

9. Power consumption of the IC

Power of the IC is consumed by the transistor of the output block and that of the logic block mainly.

$$P(\text{total}) = P(\text{out}) + P(\text{bias})$$

- Power consumption of the motor output block
Power of the output block (P(out)) is consumed by MOSFET of upper and lower H-Bridge.

$$P(\text{out}) = \text{Number of H-Bridge} \times I_{\text{out}} (\text{A}) \times V_{\text{DS}} (\text{V}) = 2 (\text{ch}) \times I_{\text{out}} (\text{A}) \times I_{\text{out}} (\text{A}) \times R_{\text{on}} (\Omega) \dots \dots \dots (1)$$

When the current waveform of the motor output corresponds to the ideal waveform (2-phase excitation / square wave), average power of output block can be provided as follows;

When $R_{\text{on}} = 0.8\Omega$, $I_{\text{out}} (\text{peak: Max}) = 1.5 \text{ A}$, $V_{\text{M}} = 24 \text{ V}$

$$P(\text{out}) = 2 (\text{ch}) \times 1.5 (\text{A}) \times 1.5 (\text{A}) \times 0.53 (\Omega) \dots \dots \dots (2)$$

$$= 2.385(\text{W})$$

- Power consumption of logic and IM systems.
Power consumptions of logic and IM systems are calculated by separating the states (operating and stopping).

$$I (\text{IM3}) = 5.0 \text{ mA (typ.) : Operating}$$

$$I (\text{IM2}) = 3.5 \text{ mA (typ.) : Stopping}$$

Output system is connected to VM (24V). (Output system: Current consumed by the circuit connected to VM + Current consumed by switching output steps)

Power consumption is calculated as follows;

$$P(\text{bias}) = 24 (\text{V}) \times 0.0050 (\text{A}) \dots \dots \dots (3)$$

$$= 0.12 (\text{W})$$

- Power consumption
Total power consumption P(total) is calculated from the values of formula (2) and (3).

$$P(\text{total}) = P(\text{out}) + P(\text{bias}) = 2.385 + 0.12 = 2.505 (\text{W})$$

Standby mode is released. The power consumption in non-operation mode of the motor (waiting mode) is calculated as follows;

$$P = 24 (\text{V}) \times 0.0035 (\text{A}) = 0.084 (\text{W})$$

In actual motor operation, the average current becomes lower than the calculated value because of transition time of the current steps and the ripple of the constant current PWM. Refer to the above equations, evaluate the heat design of the board by the actual board enough, and configure the appropriate margin.

10. Power dissipation

Relation equation of the ambient temperature (T_a), junction temperature (T_j), and the heat resistance ($R_{th(j-a)}$) between junction temperature to ambient temperature is as follows:

$$T_j = T_a + P \times R_{th(j-a)}$$

(Example) When 4-layer mounting board ($R_{th(j-a)} = 25^\circ\text{C/W}$), $T_a = 25^\circ\text{C}$, $P(\text{total}) = 2.505 \text{ W}$
 ($I_{out} = 1.5 \text{ A}$, 2-phase excitation)
 $T_j = 25 (\text{°C}) + 25 (\text{°C/W}) \times 2.505 (\text{W}) = 87.625^\circ\text{C}$

(Reference) Relation between the power dissipation and the ambient temperature

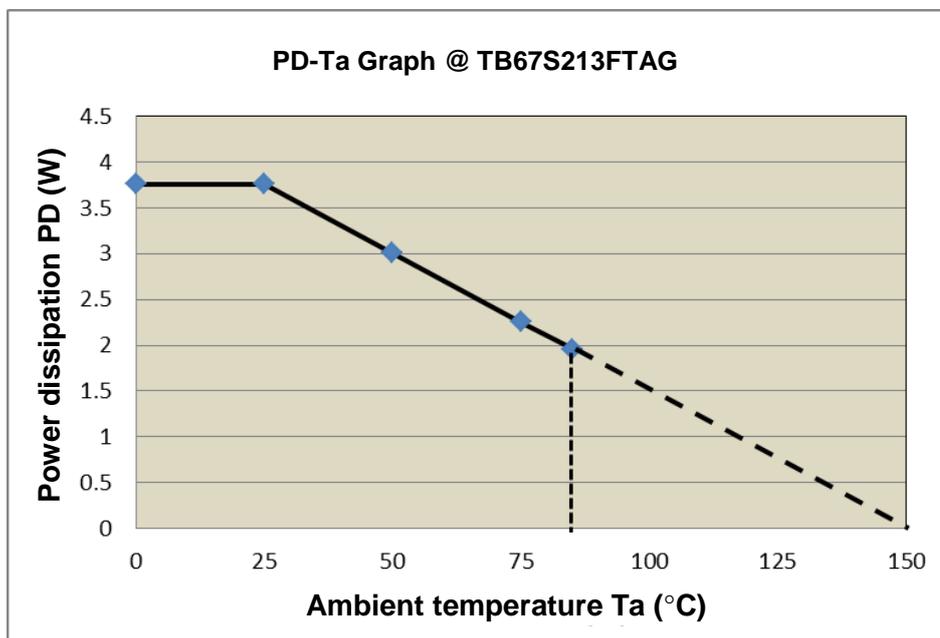


Figure 10.1 Power dissipation

* Pay attention that T_a , $R_{th(j-a)}$, and $P(\text{total})$ depend on the usage environment. When ambient temperature is high, the allowable power consumption decreases.

11. Reference land pattern example

(1) QFN36 land pattern (unit: mm)

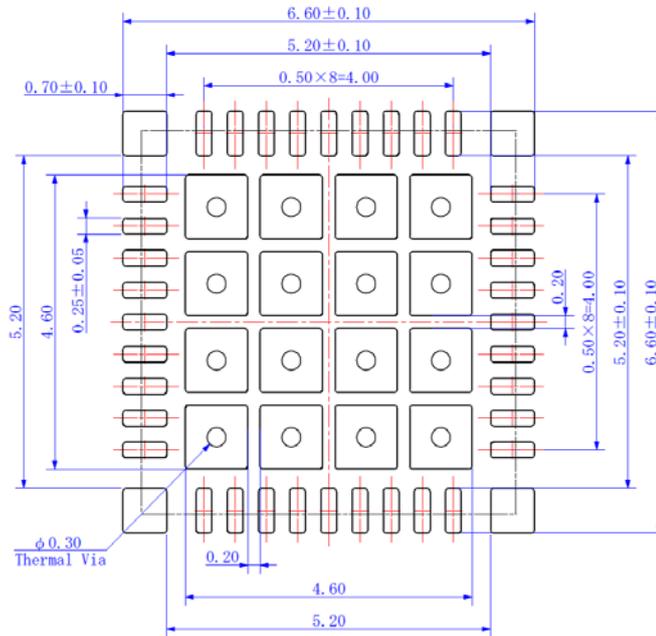


Figure 11.1 QFN36 land pattern

Toshiba does not guarantee the data for mass production. Please use the data as reference data for customer's application.

Note: In determining the size of mounting board, design the most appropriate pattern by considering the solder bridge, the solder connecting strength, the pattern accuracy in making board, the heat sink of leads, and the mounting accuracy of the IC board.

12. Board dimensions

12.1. Input

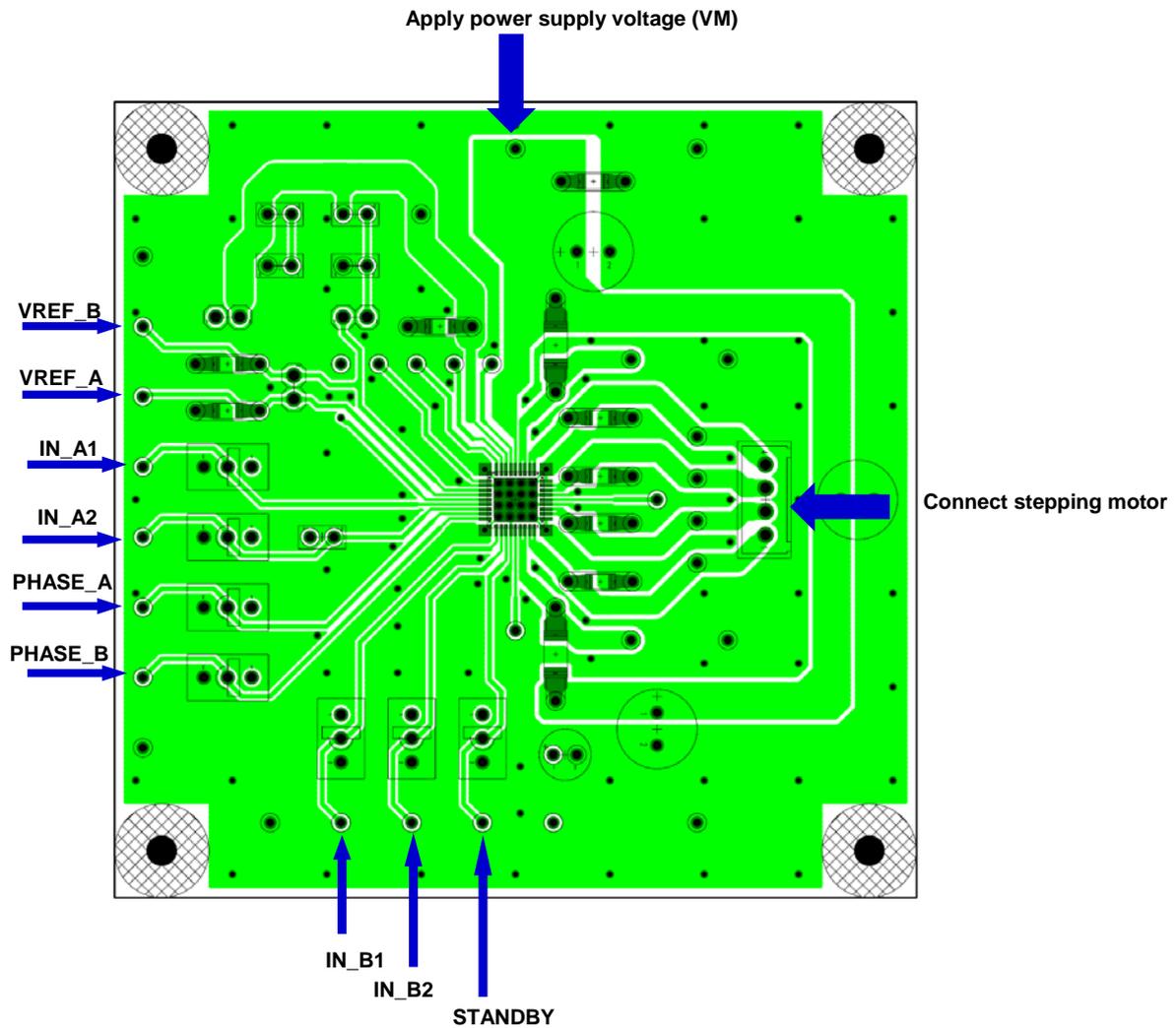


Figure 12.1 Input

Input each power supply and control signal according to above figure.

12.2. Main part

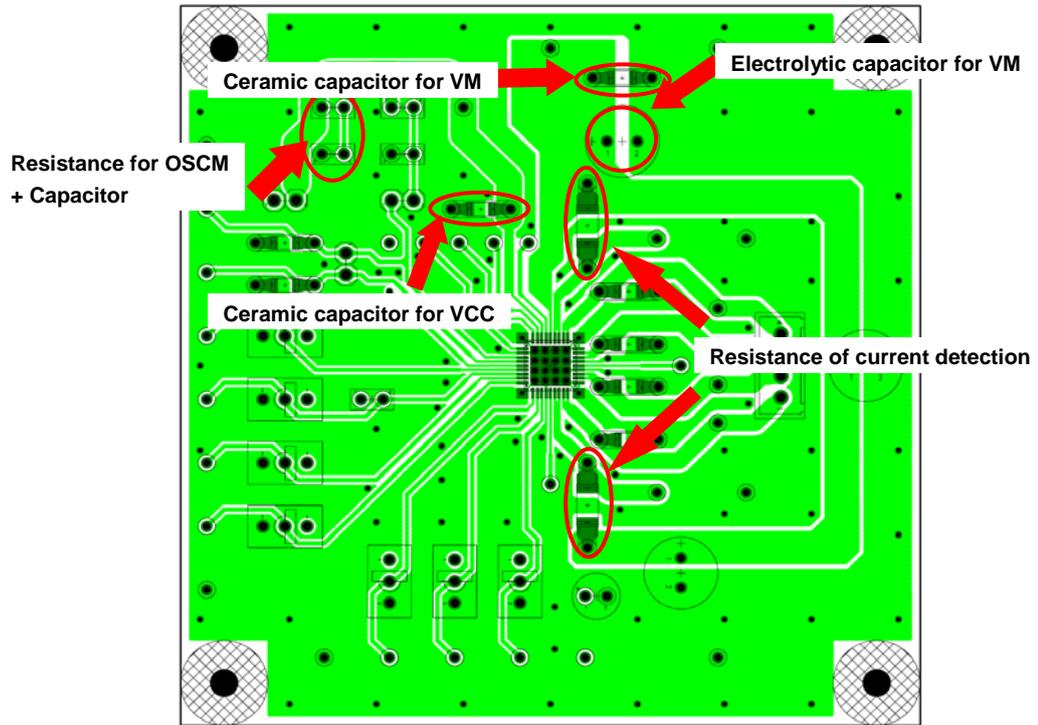


Figure 12.2 Main part

Connect each part referring to “8. Application circuit example”.

12.3. Options

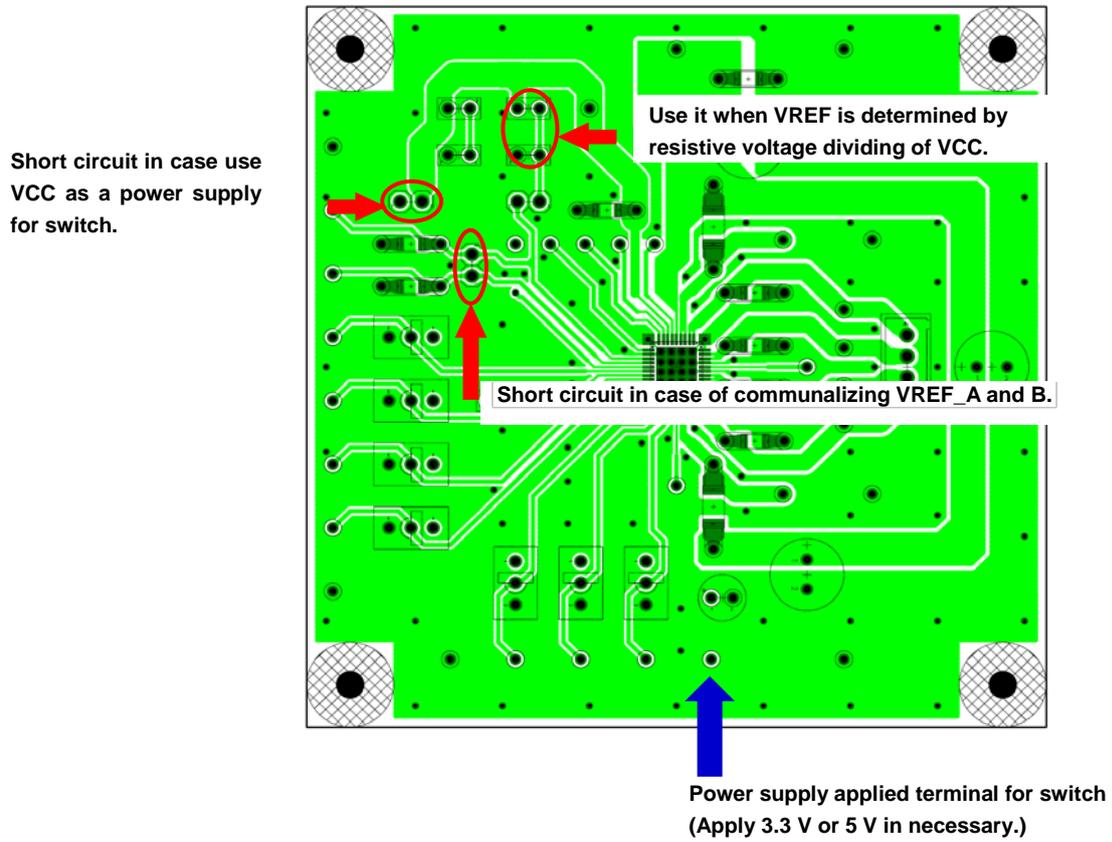


Figure 12.3 Options

Notes on Contents

1. **Block Diagrams**
Some of the functional blocks, circuits, or constants in the block diagram may be omitted or simplified for explanatory purposes.
2. **Equivalent Circuits**
The equivalent circuit diagrams may be simplified or some parts of them may be omitted for explanatory purposes.
3. **Timing Charts**
Timing charts may be simplified for explanatory purposes.
4. **Application Circuits**
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5. **Test Circuits**
Components in the test circuits are used only to obtain and confirm the device characteristics. These components and circuits are not guaranteed to prevent malfunction or failure from occurring in the application equipment.

IC Usage Considerations

Notes on handling of ICs

- (1) The absolute maximum ratings of a semiconductor device are a set of ratings that must not be exceeded, even for a moment. Do not exceed any of these ratings. Exceeding the rating(s) may cause device breakdown, damage or deterioration, and may result in injury by explosion or combustion.
- (2) Use an appropriate power supply fuse to ensure that a large current does not continuously flow in the case of overcurrent and/or IC failure. The IC will fully break down when used under conditions that exceed its absolute maximum ratings, when the wiring is routed improperly or when an abnormal pulse noise occurs from the wiring or load, causing a large current to continuously flow and the breakdown can lead to smoke or ignition. To minimize the effects of the flow of a large current in the case of breakdown, appropriate settings, such as fuse capacity, fusing time and insertion circuit location, are required.
- (3) If your design includes an inductive load such as a motor coil, incorporate a protection circuit into the design to prevent device malfunction or breakdown caused by the current resulting from the inrush current at power ON or the negative current resulting from the back electromotive force at power OFF. IC breakdown may cause injury, smoke or ignition. Use a stable power supply with ICs with built-in protection functions. If the power supply is unstable, the protection function may not operate, causing IC breakdown. IC breakdown may cause injury, smoke or ignition.
- (4) Do not insert devices in the wrong orientation or incorrectly. Make sure that the positive and negative terminals of power supplies are connected properly. Otherwise, the current or power consumption may exceed the absolute maximum rating, and exceeding the rating(s) may cause device breakdown, damage or deterioration, and may result in injury by explosion or combustion. In addition, do not use any device inserted in the wrong orientation or incorrectly to which current is applied even just once.
- (5) Carefully select external components (such as inputs and negative feedback capacitors) and load components (such as speakers), for example, power amp and regulator. If there is a large amount of leakage current such as from input or negative feedback condenser, the IC output DC voltage will increase. If this output voltage is connected to a speaker with low input withstand voltage, overcurrent or IC failure may cause smoke or ignition. (The overcurrent may cause smoke or ignition from the IC itself.) In particular, please pay attention when using a Bridge Tied Load (BTL) connection-type IC that inputs output DC voltage to a speaker directly.

Points to remember on handling of ICs**(1) Overcurrent detection Circuit**

Overcurrent detection circuits (referred to as current limiter circuits) do not necessarily protect ICs under all circumstances. If the overcurrent detection circuits operate against the overcurrent, clear the overcurrent status immediately.

Depending on the method of use and usage conditions, exceeding absolute maximum ratings may cause the overcurrent detection circuit to operate improperly or IC breakdown may occur before operation. In addition, depending on the method of use and usage conditions, if overcurrent continues to flow for a long time after operation, the IC may generate heat resulting in breakdown.

(2) Thermal Shutdown Circuit

Thermal shutdown circuits do not necessarily protect ICs under all circumstances. If the thermal shutdown circuits operate against the over-temperature, clear the heat generation status immediately.

Depending on the method of use and usage conditions, exceeding absolute maximum ratings may cause the thermal shutdown circuit to operate improperly or IC breakdown to occur before operation.

(3) Heat Radiation Design

When using an IC with large current flow such as power amp, regulator or driver, design the device so that heat is appropriately radiated, in order not to exceed the specified junction temperature (T_J) at any time or under any condition. These ICs generate heat even during normal use. An inadequate IC heat radiation design can lead to decrease in IC life, deterioration of IC characteristics or IC breakdown. In addition, when designing the device, take into consideration the effect of IC heat radiation with peripheral components.

(4) Back-EMF

When a motor rotates in the reverse direction, stops or slows abruptly, current flows back to the motor's power supply owing to the effect of back-EMF. If the current sink capability of the power supply is small, the device's motor power supply and output terminals might be exposed to conditions beyond the absolute maximum ratings. To avoid this problem, take the effect of back-EMF into consideration in system design.

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